

# ES-Series H-Pin Socket

Accelerated life testing solution



ES family Series of sockets extended the scope of a burn-in socket. The modular lid construction can handle up to 1 kW of power and is optimized with thermal simulation to ensure out-of-the-box performance whether liquid or air cooled.

Leveraging a variety of advanced manufacturing techniques and industry-leading automation enables the lowest cost of test. Our patented H-Pin technology provides versatility in the socket application which can be used for ATE and SLT functional testing, in addition to covering the full gambit of burn-in test applications. The ES family Series of sockets is designed for use with all advanced burn-in systems. With adaptation comes unmatched value in delivering cutting-edge technology.

ES-Series product meets the demanding requirements of next-generation AI, datacenter, and network accelerator applications as these cutting-edge devices get larger and more powerful. The ES socket modularity allows for the platform to evolve with each new generation of device.

Burn-in sockets using H-Pin technology for high-reliability testing of next-generation IC packages

## Benefits

- Configurable design, large tooling catalog, molding, machining, 3D printing, and assembly automation deliver best-in-class quality, price, and lead times.
- An extensive catalog of standard components provides field-tested designs.
- Double-latching clamshell provides ease of use during operation for high pin count applications.
- Thermal and electrical simulation, Monte Carlo and FEA all ensure the delivery of out-of-the-box solution.

## Feature Options

- Spring loaded plunger
- Heat sink
- HAST venting features
- Integrated thermal control with heater and sensor
- Reverse seating plane
- Maximum component clearance under the DUT
- High temperature materials for above 200 °C applications

## ES Series socket specifications

### Mechanical properties

- Pitch: 0.35 mm minimum
- Package size:
  - LGA: 27 mm to 100 mm
  - BGA: 27 mm to 100 mm
- Pin count: 7000+
- Temperature: -55 °C to 200+ °C

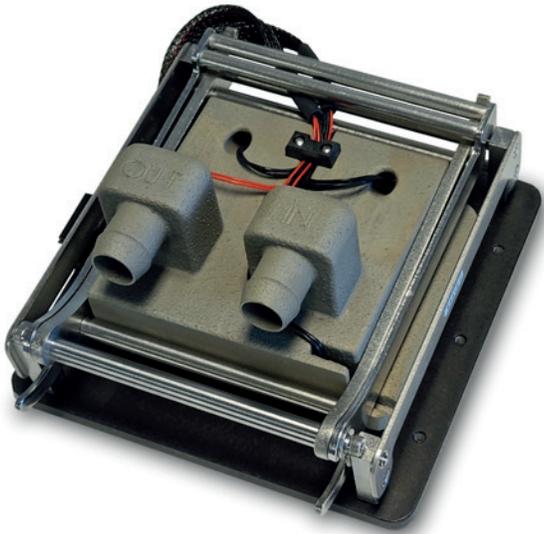
### Electrical properties

- Contact resistance: 35 mΩ
- Current carrying capacity: up to 4 A

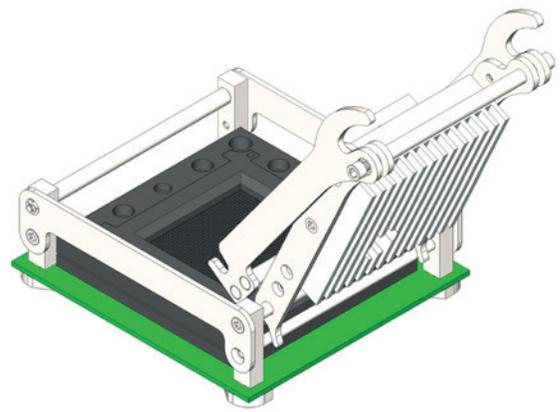
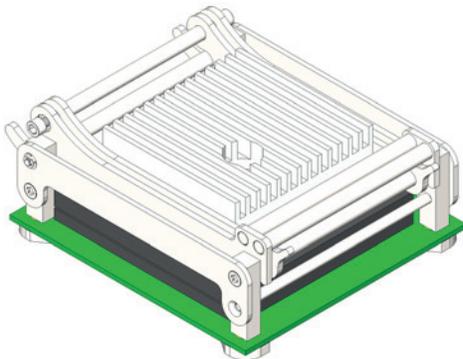
### Materials

- Contact: BeCu/Au plated
- Spring: SS/Au plated
- Socket: Engineering plastics

## ES Series socket dimensions



Liquid cooled heatsink option



Heat sink, heater and RTD, spring loaded pusher